

3D Solder Paste Inspection Machine SI-V200SPI

2D/3D Hybrid inspection machine

The proven high precision model SI-V200 equipped with 3D solder paste inspection function.

Covers all the post-printing inspections, such as foreign material, bleeding, micro-bridge, height, volume and deformity.



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2D/3D Hybrid inspection

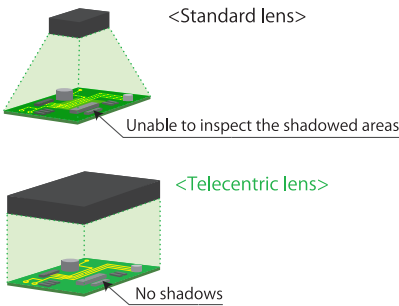
Equipped with 3D solder paste inspection to the proven high precision model SI-V200, which supports all the inspection required after solder paste printing. It also works as a normal 2D inspection machine when 3D inspection is not required.

Inspection Item	2D	3D	2D/3D
Height / Deformity	NG	OK	OK
Shape	NG	OK	OK
Dimension	OK	OK	OK
Position	OK	OK	OK
Micro Bridge	OK	*	OK
Bleeding	OK	*	OK
Foreign Material	OK	NG	OK

* Depends on case

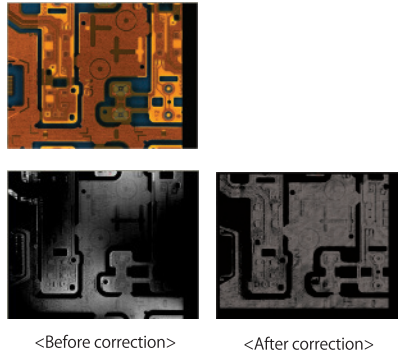
Telecentric lens

With a telecentric lens, the system is able to capture images as viewed from directly above, from corner to corner, including defects that may be hiding in the shadow of a taller part.



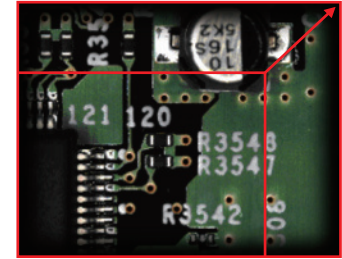
Supports flexible PWB

Original algorithm compensates warpage, which makes it possible to inspect solder paste even on flexible PWBs.



5 megapixel full color CCD camera

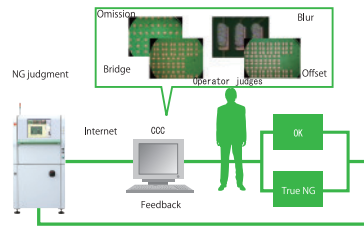
A 5 megapixel color CCD camera ensures wider screen view. It provides high speed and high accuracy at the same time.



<Full color CCD>

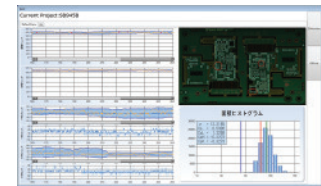
CCC (Central Confirmation Control)*

NG images obtained by multiple inspection machines are gathered into central a PC enabling a single operator to visually judge all the images alone. This prevents inconsistent judgements made by several operators.



SPC (Statistical Process Control)*

Gives managers real-time information on the status of quality. This helps them make quick decisions in the event of a problem.



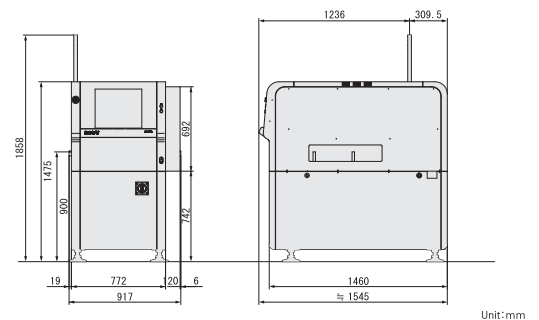
*Option

Specifications

3D Solder paste inspection Machine	
Model name	SI-V200SPI
Machine type	2D/3D Hybrid inspection machine
PWB size	50mm×40mm-510mm×460mm Thickness : 0.4mm-3.0mm
Component size range	0603(metric), cylindrical chip, tantalum capacitor, transistor, SOP/QFP, etc.
Inspection speed	2D: 0.37sec/frame, 2D + 3D : 0.77 sec/frame (Our optimum value)
Resolution	15 μm
Inspection items	2D: Area, bleeding, offset, bridge, foreign material, 3D: Height, volume, deformity etc.
Power supply	AC200V-240V ±10% 50/60Hz Max 1.5 k VA
Dimensions	W917mm×D1,545mm×H1,475mm (Excluding signal tower)
Weight	1,305kg

* Option ※ Above figures are subject to vary on the conditions. Please contact our sales reps for details.

External Dimensions



Unit:mm

⚠ Safety Precautions: To use the product safely, read and understand the contents of the instruction manual before use. ● Standards, specifications and appearance are subject to change due to continual improvements without prior notice.

Sony Manufacturing Systems Corporation
<http://www.sonysms.co.jp/>

The contents of this literature are as of April 2011